

2. HX8352-B PAD Assignment

Chip Size: 18680 um x 720 um
(Including Seal-ring 15 um*2
Scribe line 80 um*2)

Chip Thickness: 300 um (typ.)

Pad Location: Pad center

Coordinate Origin: Chip center

Au Bump Size

1. 24 um x 120 um
Input/Output
(No. 1 ~ No. 439)
2. 14 um x 106 um
Staggered LCD output side
(No. 437 ~ No. 658)
3. 14 um x 106 um
Staggered LCD output side
(No. 659 ~ No. 1412)
4. 14 um x 106 um
Staggered LCD output side
(No. 1413 ~ No. 1634)

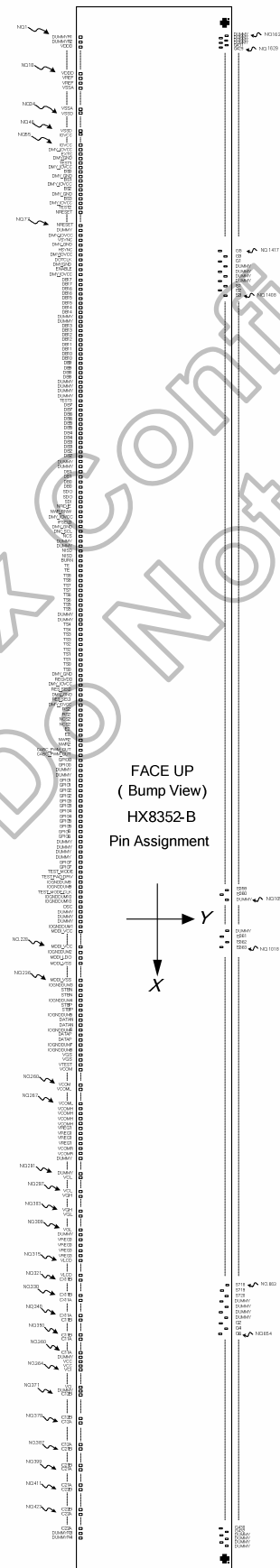


Figure 2.1 HX8352-B pad assignment

>>HX8352-B

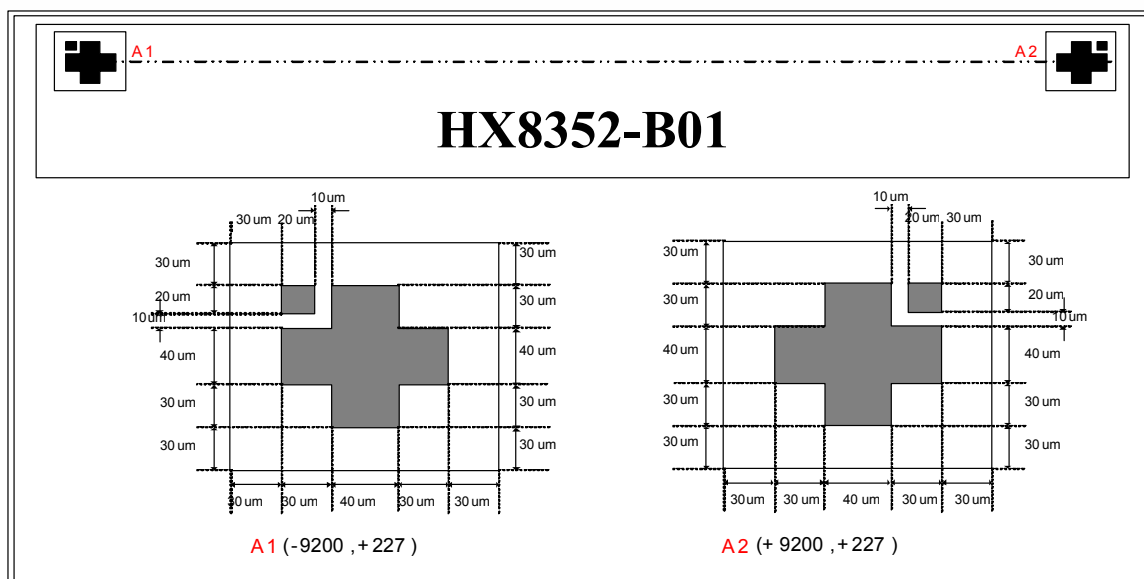
240RGB x 432 dot, 262K color, TFT Mobile Sir

APPLICATION NOTE V01

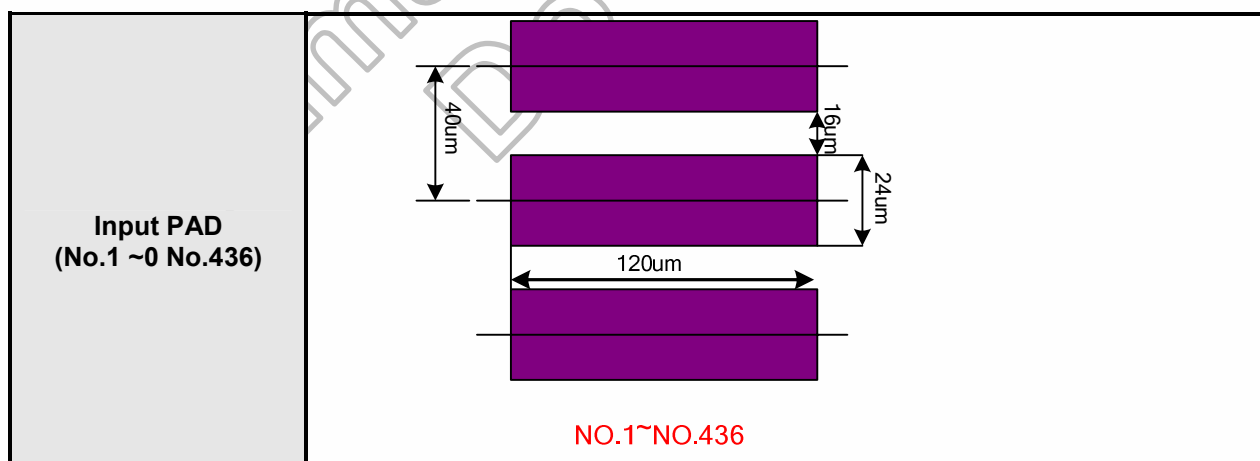
2.1 Alignment mark

HX8352-B01 Alignment mark

-+	A1	-9200	227
++	A2	9200	227



2.2 Bump size

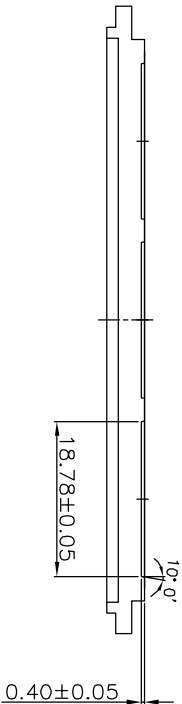




Technical drawing of a rectangular plate. The drawing shows a rectangular plate with a center cross (dashed lines). The dimensions are indicated on the right side:

- Overall width: 71.0 ± 0.1
- Inner width: 68.3 ± 0.1

SECTION A



Remark :
1. Height of text: Max. 0.1mm

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2. Tray material: ABS
3. Tray Color Code: Black
4. Surface Resistance: $10^9 \sim 10^{11} \Omega$
5. Tray Warpage: Max. 0.10mm
6. Unspecified Dimensions tolerance: $\pm 0.15\text{mm}$
7. Pocket size: 18.78x0.82x0.4mm
8. IC size: 18.68x0.72x0.3mm
9. Himax product name: HX8352-BPD300
10. Bottom of Pocket: Rough Surface.

NO.	DESCRIPTION	MATERIAL	QTY	REMARK	 HWA SHU	REV.
	COG TRAY	—	—	—		
APP.	CHK	DS	DR	THIRD ANGLE PROJECTION	SCALE	TOLERANCE
						
		2003-07-14 虹月			DWG. NO.	H30-739x32-16(78)-01
						H30-739x32-16(78)-HS
					ID. CODE	00